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GaN HEMT 50V, 500W,2.1-2.2GHz RF Power Transistor

Description

The STBV22500BY4 is a dual path 500watt , Input matched GaN HEMT, ideal for applications from 2.1 to 2.2 GHz especially for LTE/5G

There is no guarantee of performance when this part is used outside of stated frequencies.

Typical RF performance on asymmetrical Doherty with device soldered

VDS= 50V, IDQ=150mA(Vgm=-3.07V, Vgp=-5.50V)

Pulsed CW: 20uS width, 10% cycle.

Freq	P3dB	P3dB	P3dB	P3dB	P5dB	P5dB	P5dB
(MHz)	(dBm)	(W)	Eff(%)	Gain(dB)	(dBm)	(W)	Eff(%)
2110	56.27	423.64	67.52	14.51	57.37	545.14	63.24
2140	55.94	392.64	69.39	14.73	57.26	532.07	66.97
2170	55.84	383.71	71.06	14.50	57.15	518.80	70.14

WCDMA 1 carrier performance

Freq	Pout	CCDF	ACPR	Gain	Efficiency
(MHz)	(dBm)	(dB)	(dBc)	(dB)	(%)
2110	49	7.72	-26.44	15.79	60.25
2140	49	7.68	-27.26	15.75	60.12
2170	49	7.56	-28.51	15.37	59.25

Recommended driver:

Class AB (1 stage discrete solution): STAV38041C6

Applications

- Asymmetrical Doherty amplifier within 2.1-2.2GHz
- S band power amplifier
- CW or pulsed Amplifier

Important Note: Proper Biasing Sequence for GaN HEMT Transistors

Turning the device ON

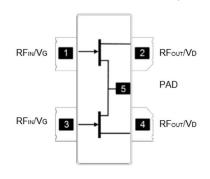
- 1. Set VGS to the pinch--off (VP) voltage, typically -5~V
- 2. Turn on VDS to nominal supply voltage
- 3. Increase VGS until IDS current is attained
- 4. Apply RF input power to desired level

Turning the device OFF

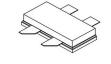
- 1. Turn RF power off
- 2. Reduce VGS down to VP, typically -5 V
- 3. Reduce VDS down to 0 V
- 4. Turn off VGS

Figure 1: Pin Connection definition

Transparent top view (Backside grounding for source)



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Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
DrainSource Voltage	V _{DSS}	+200	Vdc
GateSource Voltage	V _{GS}	-8 to +0.5	Vdc
Operating Voltage	V _{DD}	55	Vdc
Maximum gate current	Igs	61	mA
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	T _C	+150	°C
Operating Junction Temperature	TJ	+225	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case by FEA	Dolo	1	00 00
T _C = 85°C, at Pd=105W, on Doherty application board	Rejc	1	°C /W

Table 3. Electrical Characteristics (TA = 25℃ unless otherwise noted)

DC Characteristics (Main path, measured on wafer prior to packaging)

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage	VGS=-8V; IDS=25.2mA	V _{DSS}		200		V
Gate Threshold Voltage	VDS =10V, ID = 25.2mA	$V_{GS(th)}$	-4		-2	V
Gate Quiescent Voltage	VDS =50V, IDS=150mA, Measured in Functional Test	$V_{GS(Q)}$		-3.07		V

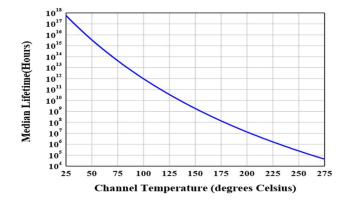
DC Characteristics (Peak path, measured on wafer prior to packaging)

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage	VGS=-8V; IDS=39.6mA	V _{DSS}		200		V
Gate Threshold Voltage	VDS =10V, ID = 39.6mA	$V_{GS(th)}$	-4		-2	V
Gate Quiescent Voltage	VDS =50V, IDS=150mA, Measured in Functional Test	$V_{GS(Q)}$		-3.0		V

Ruggedness Characteristics

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Load mismatch capability	2.14GHz, Pout=90W WCDMA 1					
	Carrier in Doherty circuit	VCMD		10.1		
	All phase,	VSWR		10:1		
	No device damages					

Figure 2: Median Lifetime vs. Channel Temperature



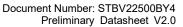




Figure 3: Efficiency and power gain as function of Pout (2.1-2.2GHz Doherty)

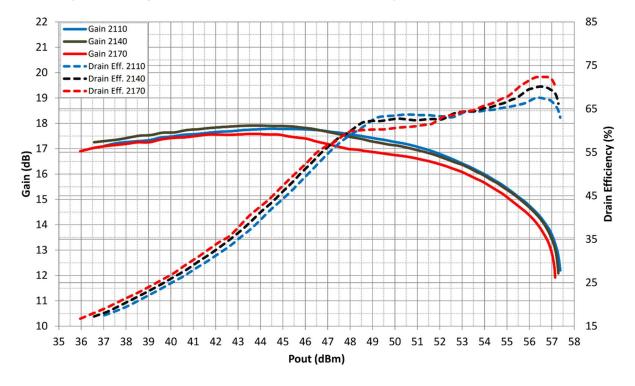
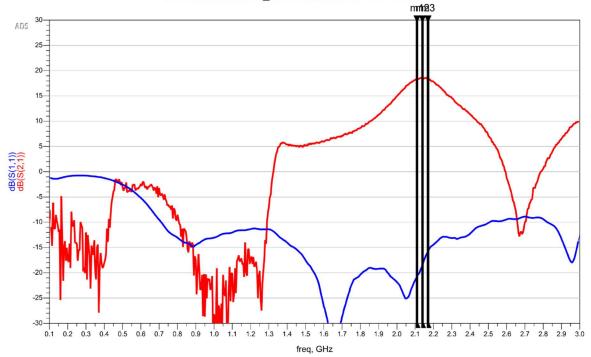


Figure 4: Network analyzer output, S11 and S21 (2.1-2.2GHz Doherty)

m1 freq=2.110 GHz dB(S(2,1))=18.401 dB(S(2,1))=20.740 dB(S(2,1))=18.567 dB(S(2,1))=18.379 dB(S(1,1))=-15.781

S-Parameters_STBV22500BY4 DHT



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Figure 5: Picture of application board Doherty circuit for 2.1-2.2GHz

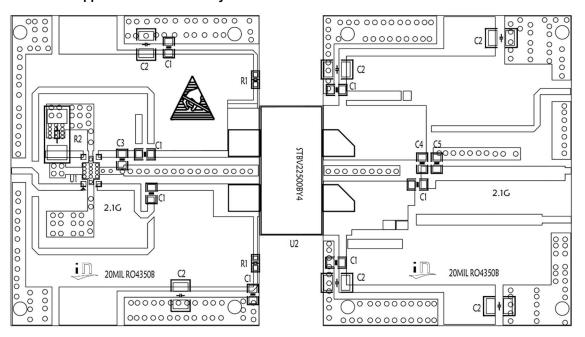
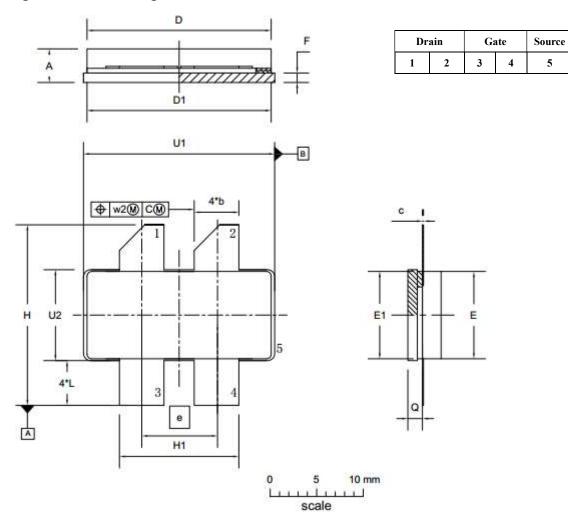


Table 4. Bill of materials of application board (PCB layout upon request, RO4350B 20mils)

Reference	Footprint	Value	Quantity
C1	0805	18pF/250V	7
C2	1210	10uF/100V	6
C3	0805	0.4pF/250V	1
C4	0805	2.2pF/250V	1
C5	0805	0.3pF/250V	1
R1	0603	10R	2
R2	2512	51R	1
U1	6.35*5.08mm	HC2100P03H	1
U2	BY4	STBV22500BY4	1

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Earless Flanged Ceramic Package; 4 leads



UNIT	A	b	С	D	D ₁	е	E	E ₁	F	Н	H1	L	Q	U ₁	U ₂	W ₁	W ₂
mm	4.72	4.67	0.15	20.02	19.96	7.90	9.50	9.53	1.14	19.94	12.98	5.33	1.70	20.70	9.91	0.25	0.51
"""	3.43	4.93	0.08	19.61	19.66	7.30	9.30	9.25	0.89	18.92	12.73	4.32	1.45	20.45	9.65	0.23	0.51
inahaa	0.186	0.194	0.006	0.788	0.786	0.211	0.374	0.375	0.045	0.785	0.511	0.210	0.067	0.815	0.390	0.01	0.00
inches	0.135	0.184	0.003	0.772	0.774	0.311	0.366	0.364	0.035	0.745	0.501	0.170	0.057	0.805	0.380	0.01	0.02

OUTLINE		REFERENCE		EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA	PROJECTION	1000E DATE
PKG-B4					03/12/2013



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Revision history

Table 4. Document revision history

Date	Revision	Datasheet Status
2021/6/1	V1.0	Preliminary Datasheet Creation
2021/8/25	V1.1	Add recommended driver
2022/5/17	V1.2	Modify the recommended band and driver
2022/9/30	V2.0	Modify according to configuration of main path and peak path

Application data based on: ZBB-22-11

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